

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/25/15910
1.3 Title of PCN	ASE Kaohsiung (Taiwan) additional source for STM32F446x listed products in LQFP 10x10 64L package
1.4 Product Category	STM32F446x
1.5 Issue date	2025-11-04

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.2.2 Marketing Manager	Veronique BARLATIER
2.2.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE Kaohsiung (Taiwan)

4. Description of change

	Old	New
4.1 Description	Current assembly sites: - JSCC (China) in Gold, Silver or Copper Palladium wire	Current assembly site : - JSCC (China) in Gold, Silver or Copper Palladium wire Additional assembly site for extended capacity: - ASE Kaohsiung (Taiwan) in copper palladium wire
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	no impact on Form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST Internal tools
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7. Timing / schedule

7.1 Date of qualification results	2025-10-29
7.2 Intended start of delivery	2026-02-04
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	15910 MDG-GPM-RER2304-PCN13841 14224 14728 15910 V4-ASE LQFP7 to 20 CuPd wire-RER report.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2025-11-04
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9. Attachments (additional documentations)

15910 Public product.pdf
 15910 MDG-GPM-RER2304-PCN13841 14224 14728 15910 V4-ASE LQFP7 to 20 CuPd wire-RER report.pdf
 15910 _Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F446RCT6	
	STM32F446RCT6TR	
	STM32F446RCT7	
	STM32F446RCT7TR	
	STM32F446RET6	
	STM32F446RET6TR	
	STM32F446RET7	
	STM32F446RET7TR	

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